



Practical AI Networking Innovations

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My 30 Year Journey















Hyperscalers AI Infrastructure

POSTED ON MARCH 12, 2024 TO AI RESEARCH, DATA CENTER ENGINEERING, ML APPLICATIONS

Building Meta's GenAl Infrastructure



By the end of 2024, we're aiming to continue to grow our infrastructure build-out that will include 350,000 NVIDIA H100 GPUs as part of a portfolio that will feature compute power equivalent to nearly 600,000 H100s.

ORACLE Inside OCI Supercluster

OCI Supercluster: The Infrastructure Driving Generative AI at Scale (0:55)

Run the most demanding AI workloads faster, including generative AI, computer vision, and predictive analytics, anywhere in our distributed cloud. Get the latest GPU compute, scaling up to the 32,768 GPU Oracle Cloud Infrastructure (OCI) Supercluster.

AWS Teases 65 Exaflop 'Ultra-Cluster' with Nvidia, Launches New Chips



Google Cloud claims 'most powerful' publicly available machine learning cluster

Announcing Trillium, the sixth generation of Google Cloud TPU

https://engineering.fb.com/2024/03/12/data-center-engineering/building-metas-genai-infrastructure/

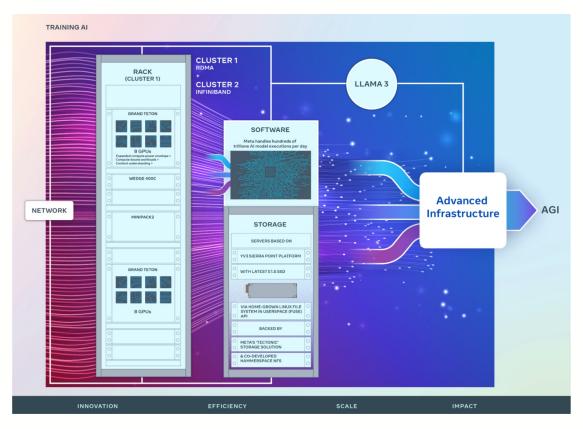
Empowering Azure Storage with RDMA : Today, around 70% of traffic in Azure is RDMA and intra-region RDMA is supported in all Azure public regions. <u>https://www.microsoft.com/en-us/research/uploads/prod/2023/03/RDMA_Experience_Paper_TR-1.pdf</u>

Nvidia launches AI foundry on Microsoft Azure https://www.sdxcentral.com/articles/news/nvidia-launches-ai-foundry-on-microsoft-azure/2023/11/

Tesla Unveils Top AV Training Supercomputer Powered by

The cluster uses 720 nodes of 8x <u>NVIDIA A100 Tensor Core GPUs</u> (5,760 GPUs total) to achieve an industry-leading 1.8 <u>exaflops</u> of performance.

Meta GenAl Llama3 Infrastructure



Meta Built a 24k GPU Ethernet Cluster

"Through careful co-design of the network, software, and model architectures, we have successfully used both RoCE and InfiniBand clusters for large, GenAI workloads (including our ongoing training of Llama 3 on our RoCE cluster) without any network bottlenecks."

"With this in mind, we built one cluster with a remote direct memory access (RDMA) over converged Ethernet (RoCE) network fabric solution based on the Arista 7800..."

https://engineering.fb.com/2024/03/12/data-center-engineering/building-metas-genai-infrastructure/

AI Applications - Driving intense network demand

Morgan Stanley - Chatbot for Financial Advisors

- Built on GPT-4
- Trained with 100,000 curated research documents
- Provides expert advise to financial advisors
- Transparently provides answers, reasoning and sources
- Currently piloting with 300 advisors, planning to rollout to 16,000 in summer

IBM – Project Photoresist

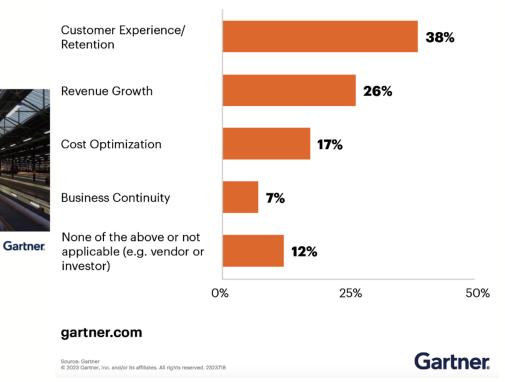
- Identifying a new molecule typically takes 10 years and costs 10-100 million
- Project photoresist was able to reduce that to months
- IBM developed a new photoacid generator, which is used in lithography, a key process in developing computer chips
- 100 times faster than traditional methods.



- Previously used external production and voice actors
- Generative video cut the time to produce a video by 95%
- Created 500 training videos in 6
 months
- Able to quickly adapt video content rather than re-start
 Diverse avatars and voices
- Diverse avatars and voices enable inclusion





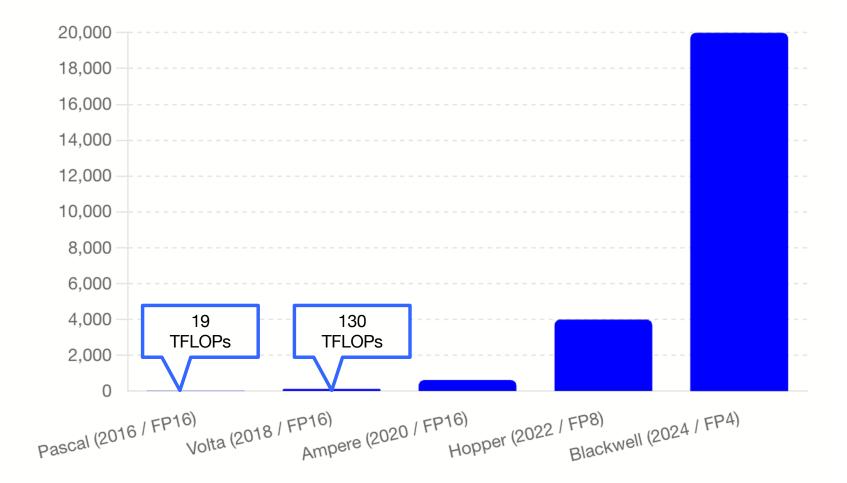




Improved Performance per GPU - Nvidia

From Pascal to Blackwell, GPU performance has increased by 1,053x

Lower Floating Point (FP) results in lower precision and lower range but also lower bandwidth and memory requirements



Blackwell Creates First-Ever FP4 Generative AI Image

FP4-quantized model produces the "4-bit Bunny"



Model using FP16

Model using FP4

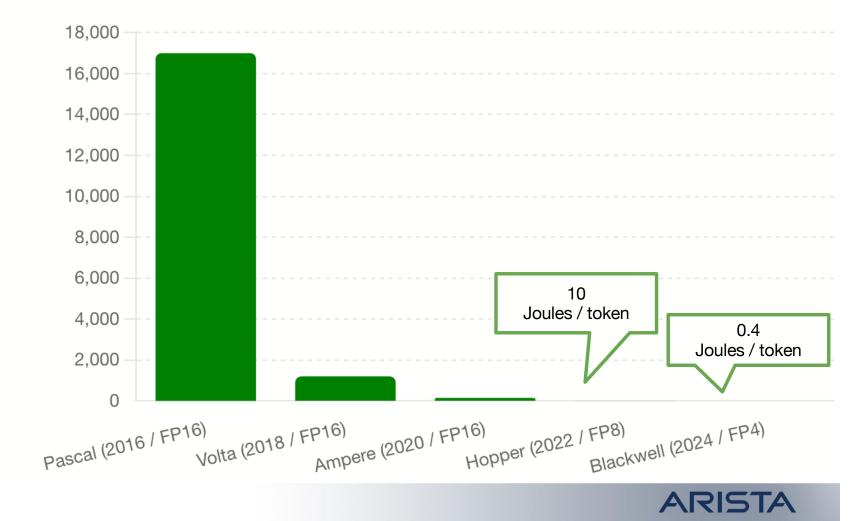
Prompt: Close up photo of a rabbit, forest in spring, haze, halation, bloom, dramatic atmosphere, centered, rule of thirds, 200mm 1.4f macro shot



Improved Energy Consumption per Token - Nvidia

Current LLMs average 3 tokens / word 4 characters / token

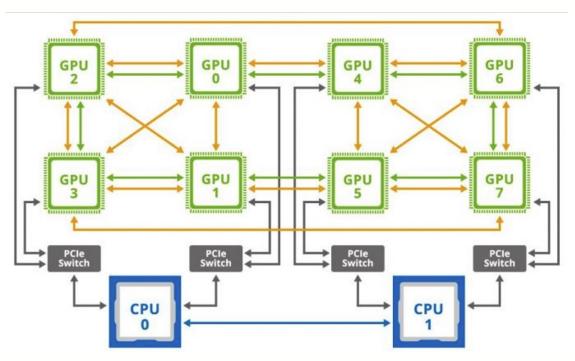
From Pascal to Blackwell, the energy consumption for token generation has dropped by 45,000x



What do these servers look like - NVIDIA example



DGX = an NVIDIA built system HGX = an OEM built system (SuperMicro, Dell, HPE) GPU collective = NCCL

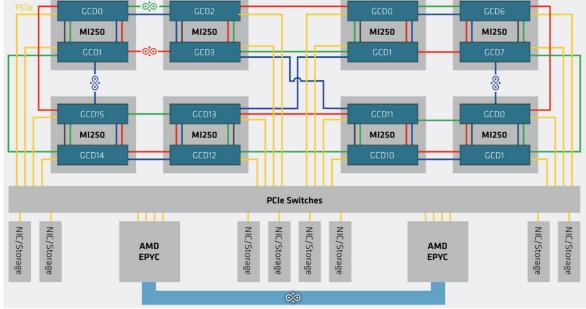


Internal CPU <-> GPU and GPU <-> GPU is a mix of PCIe and NVLink

What do these servers look like - AMD example



GPU collective = RCCL



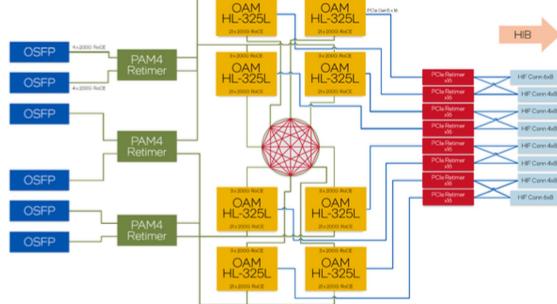
SuperMicro, Dell, HPE

Internal CPU <-> GPU and GPU <-> GPU is a mix of PCIe and Infinty

What do these servers look like - Intel example

GPU collective = HCCL





SuperMicro, Dell, HPE

Internal CPU <-> GPU and GPU <-> GPU is a mix of PCIe and Alternative Pathways

Power Requirements

Rough Calculations:

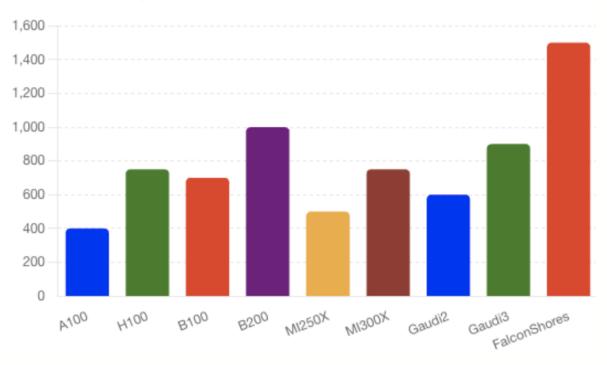
8 x 750W GPU + 500W server = 6,500W Host

Normal DC Rack = 6-10kW GPU Racks = 16-20kW

Average DC capacity ~10MW 15k GPUs =18MW 100k GPUs = 150MW

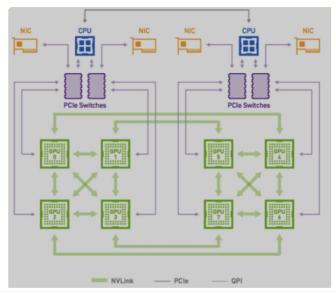


Power Draw (W) by S GPU Model



Quick note of "networks" involved GPU-to-GPU inside the host

NVIDIA = NVLink

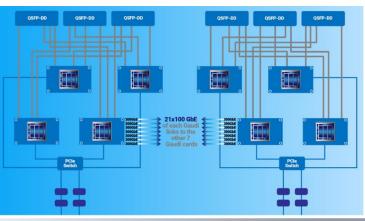




https://www.hpcwire.com/2024/05/30/everyone-except-nvidia-forms-ultra-accelerator-link-ualink-consortium/

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Intel

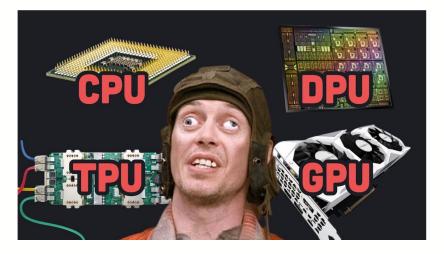




Options for xPU Connectivity

xPU is the collective name for:

- **GPU:** optimized for parallel processing, making them ideal for training large AI models with uniform data. (NVidia)
- **TPU:** specialized for TensorFlow-based AI workloads (developed by Google for neural networks), offering extreme efficiency for specific tasks.
- **DPU:** Deep learning (or Data) Processing Unit, optimised for data and often embedded in SmartNICs (NVIDIA Bluefield2 /AMD (Pensando) / Marvell)



There are three methods to connect xPU's:

- → **PCI Bus:** A standard server can usually support 4-8 GPUs across the PCI bus.
- → xPU to xPU Interconnect: Nvidia created NVLink, a GPU-to-GPU connection that can currently transfer data at 1.8 terabytes per second between GPUs. There is also an NVLink rack-level Switch capable of supporting up to 576 fully connected GPUs in a non-blocking compute fabric (single computational domain). There is currently work in progress to develop Ultra Accelerator Link (UALink), establishing an open industry standard that will enable AI accelerators to communicate more effectively.
- Server-to-Server Interconnect: Ethernet or InfiniBand (Nvidia) can connect servers that contain xPUs. This connection level is often called scale-out, where faster multi-GPU domains are connected by Ethernet/IP or IB fabric networks to form large computational networks. Recently, the Ultra Ethernet Consortium (UEC) was formed to deliver everyone else's "InfiniBand."

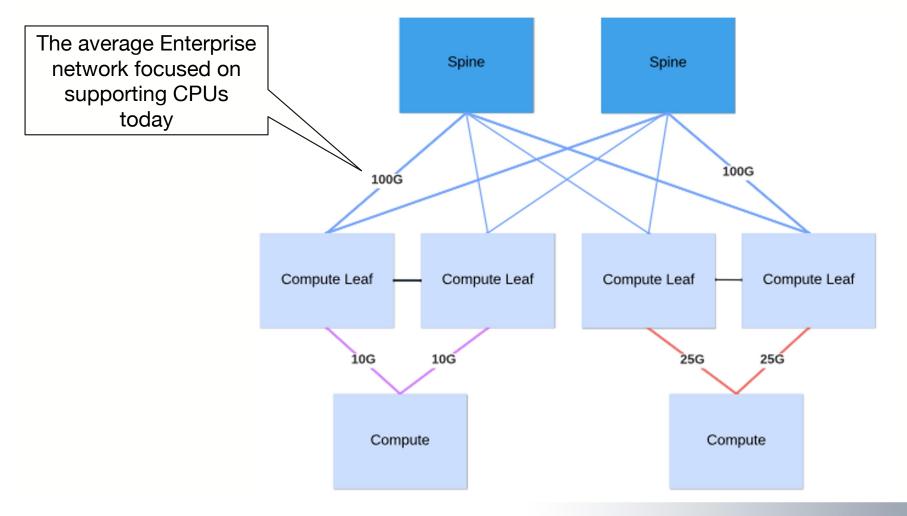


Frameworks for Managing GPU's

- NCCL NVIDIA Collective Communication Library
- RCCL AMD ROCm Collective Communication Library
- PyTorch Opensource
- Tensorflow Opensource developed by Google
- Keras Opensource
- CNTK Microsoft Cognitive Toolkit
- SageMaker AWS

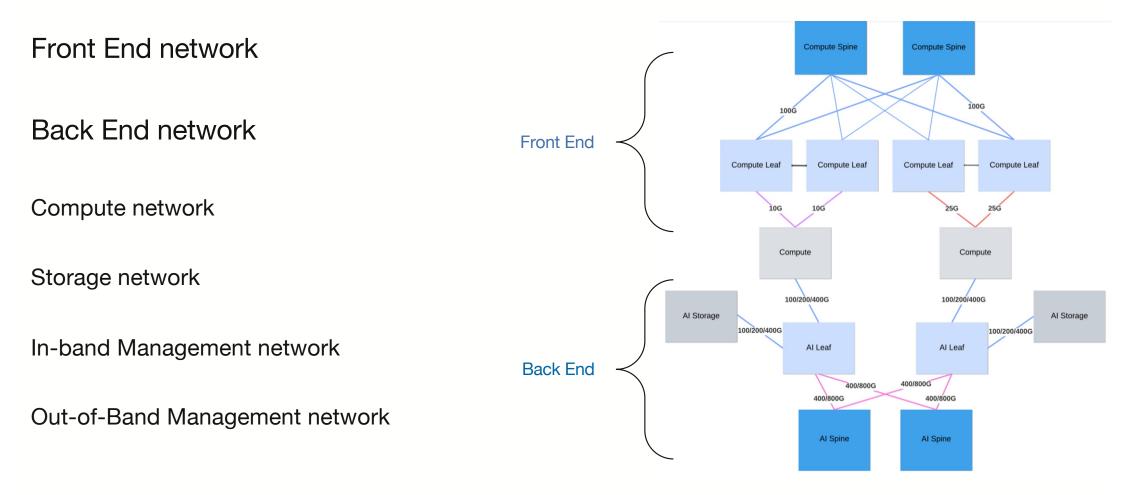


Surprise! I've got 200GbE / 400GbE xPU NICs, where should I plug them in?

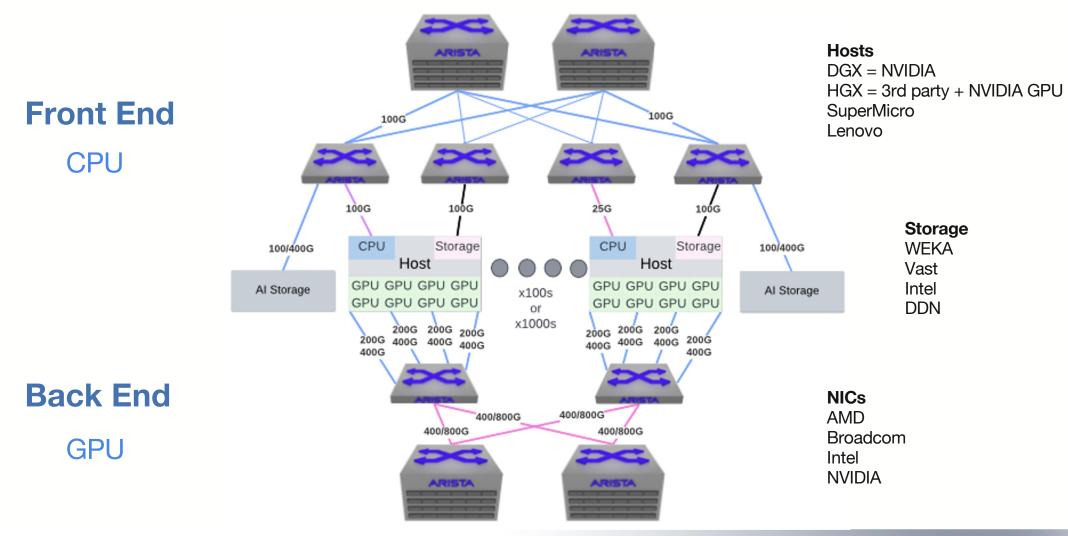




Networking for AI - What comprises an AI Infrastructure?



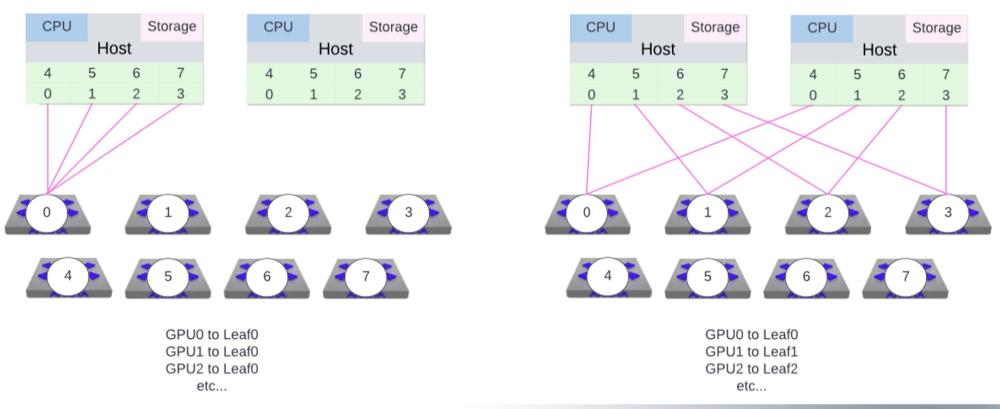
Networking for AI - What do these clusters look like?



Networking for AI - GPU Connectivity Options

Standard

A rail is comprised of GPUs that have the same rank within different hosts/clusters and are connected to the same network switch.



Rail Optimized

Networking for AI - GPU Connectivity Options

GPU0 in Host1 needs to

Host1's GPU3.

traffic to Leaf3.

Host2's GPU3.

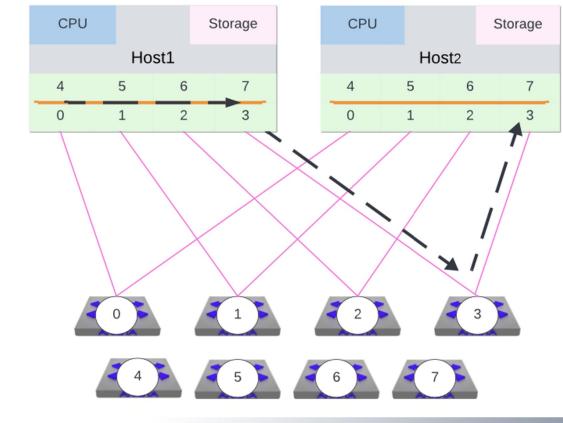
communicate with GPU3 in Host2:

GPU0 will leverage the NVLink pathway internal to Host1 to reach

Host1's GPU3 will then send that

Leaf3 sends the traffic down to

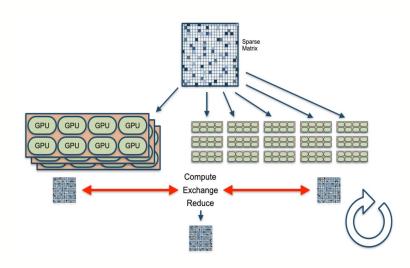
A rail is comprised of GPUs that have the same rank within different hosts/clusters and are connected to the same network switch.



Rail Optimized

AI Workloads

- Al workloads are extremely computational intensive and exceed the memory available on a single GPU therefore the workload is split across a cluster of GPU's
- These GPU's perform execute algorithms and calculations and then share results amongst each other. There are several ways of doing this commonly used term is "Collective Operation" they include Broadcast, Reduce, Ring and All-Reduce
- All GPU's have to wait until all GPU's have shared their messages and passed on results, the workload is stalled until this happens, commonly used term is "Barrier"
- GPU's within a host have their own internal fabric





What's different about AI workloads?

- Most AI workloads use collective communication for parallel computation
- Use RDMA (kernel bypass) for better performance
- Traffic characteristics
 - Tight time synchronization between traffic flows
 - Small number of large sized flows ~2 flows per NIC
 - Very little entropy
 - Short periodic bursts of network activity followed by compute
- Highly susceptible to collisions
- Job Completion Time (JCT) key metric measures time between:
 - Launching a job
 - Processing the data across the cluster of GPU/Accelerator resources
 - Posting the results
- Time Spent in Networking (TSN)
- Slowest member determines performance

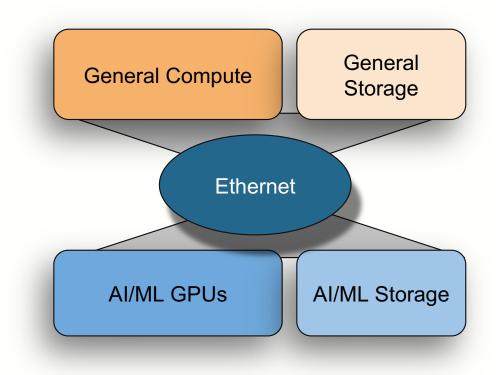
Matrix/Tensor Input Process GPU lterate All Gather GPU Output

AI Training Workloads Are Highly Co-ordinated - Sensitive to Delayed Jobs



Requirement for AI Networks

- Scale Out Capacity
- A fast, lossless network with zero oversubscription and often over provisioned.
 - for many forms of communication ALL-REDUCE, BROADCAST, ALL-TO-ALL, RING
 - Graceful handling of large synchronized flows
- Fast transfer from host to network (RDMA over Converged Ethernet)
- Visibility and telemetry
 - to identify bottlenecks in the network or application
- **Reliable and Resilient**
- Open and Interoperable

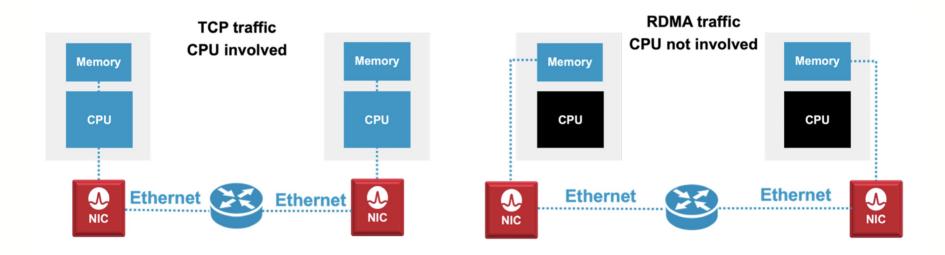


Al Workloads require a dedicated high performing lossless network



RDMA

Remote Direct Memory Access (RDMA) is the remote memory management capability that allows server-to-server data movement directly between application memory without any CPU involvement.





RDMA Over Converged Ethernet (RoCEv2)

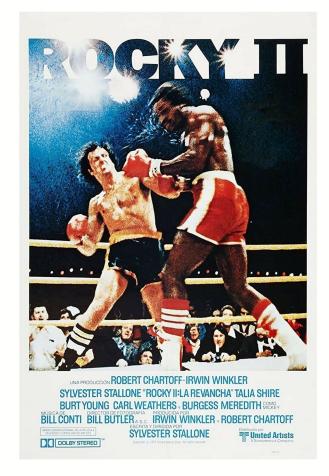
RoCE (RDMA over Converged Ethernet) is a network protocol that allows RDMA over an Ethernet network.

RoCEv2 extends the functionality and scalability of ROCE, adding a UDP/IP header

Broadcom/Intel/Nvidia Ethernet Adapters support RoCEv2 in hardware and allows for higher throughput, lower latency, and lower CPU utilization, which are critical for AI/ML, Storage, and High-Performance Compute (HPC) applications.

RoCEv2 provides the following advantages:

- Operation on routed ethernet networks, ubiquitous in large scale-out leaf-spine data centers
- IP QoS The DiffServ code point (DSCP)
- IP congestion control Explicit congestion notification (ECN)
- UDP header provides more entropy for better ECMP



Infiniband versus Ethernet

Proprietary NVIDIA

Single hop

Current products top out at 400GbE

Centralized Control Plane

"Subnet Manager" controls entire network

Industry Standard

800GbE and beyond

Distributed Control Plane

Routing protocols make local decisions

ROCEv2 brought Layer 3/IP support (multihop / scale-out)

Eth L2 Header	Ethertype	IP Header	UDP Header	IB BTH (L4 Header)	IB Payload	ICRC	FCS
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RoCEv2 frame: InfiniBand over Ethernet



Ultra Ethernet Consortium (UEC)

- Formed in the 2023, the UEC aims to develop a new standard for interconnection for AI and HPC data center requirements
 - 55+ members
- Next generation AI/HPC transport
 - Multi-Pathing and Packet Spraying
 - Flexible Ordering
 - HPC/AI optimized congestion control
 - End-2-End telemetry
 - Security

Steering Members AMDI ARISTA BROADCOM Hewlett Packard Enterprise intel.

Applications Software APIs (*CCL, MPI, OpenSHMEM) UEC extensions Libfabric Transport **Message Semantics** Packet Delivery **Congestion Management Reliability Modes** Security **IP Layer Ethernet Link Layer** LLDP Negotiation Packet Rate Improvement Logical Link Control or other MAC Client Link Level Retry MAC Control MAC **Ethernet PHY Layer FEC Statistics UEC LL Support** UEC 100 Gb/s/lane UEC 200 Gb/s/lane **PMA** PMD packets Ethernet Fabric

SOFTWARE Worker

A LINK Worker

PHYSICAL Work

UEC Stack



Ethernet Powers the Future for Generative AI Clusters

Ethernet Advantages over Infiniband for GenAl Networking Fabrics

Most Consistent Architecture

- Ethernet is native to all other systems in a data center ecosystem
 - Data warehouses
 - OLTP systems
 - Systems mgmt.
 - All others
- Infiniband stands alone on a unique island

Highest Performance for Lossless Al

- Highest performance for lossless, low latency Al job completion time
- Highest capacity for massive-scale GenAl training clusters, using 800G capable switches with clear path to 1.6T

Open Innovation for the Future

- Ethernet offers a rich, open ecosystem with multiple vendors
- Infiniband forces lock-in
- Ultra Ethernet Consortium (UEC) is advancing state of the art for GenAl flow control, scale & security



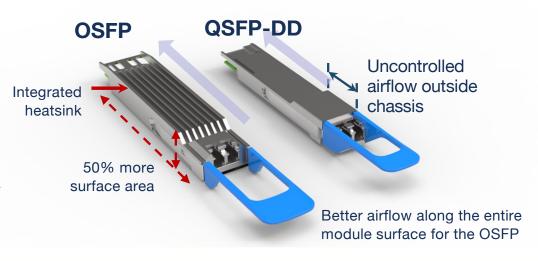
What's different about AI Connectivity?

- Higher speeds to the NIC
 - 200G and 400G connectivity to the NIC is common
 - Serdes speeds at 50G PAM-4 or 100G PAM-4
- More frequent use of AECs, AOCs and Optics for NIC Connectivity
 - Copper DACs still the cheapest option, but limited reach at higher speeds
 - Connecting NICs across multiple racks may require AOCs or optics
 - Conversion between 50G PAM-4 / lane and 100G PAM-4 / lane may be required
- Connectivity between switch vendors
 - Understand the NIC port Ethernet speed, electrical lane speed, and physical form-factor
 - Multiple options for the same Ethernet speed!!
 - "400G" port could mean:
 - 1. QSFP-DD or OSFP port using 8x 50G electrical lanes
 - 2. OSFP Riding Heat Sink (RHS) port using 4x 100G electrical lanes
 - 3. QSFP-DD port using 4x 100G electrical lanes
 - 4. QSFP112 port using 4x 100G electrical lanes



OSFP Versus QSFP-DD 400G - Thermal Performance

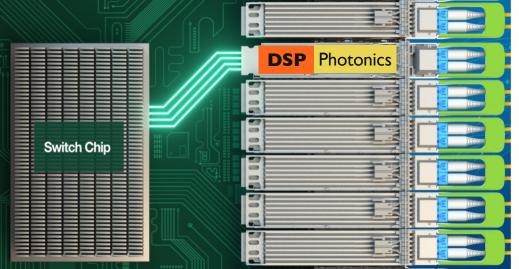
- Integrated heatsink directly attached to temp sensitive components
- ~50% Greater surface area and volume
- Better airflow across entire surface of the module
- OSFPs operate ~10 to 15C cooler than QSFP-DDs for equivalent platforms
- Lower operating temperatures dramatic increase in optics reliability
- +10C temp increases optics failure rate by ~2x
- Easier to cool Lower system fan speeds
- ~10% 25% less overall system power
- OSFP has clearer roadmap to 800G, 1.6T (OSFP-XD) and beyond
- Further efficiencies with upcoming Linear-Drive Pluggable Optics (LPO)



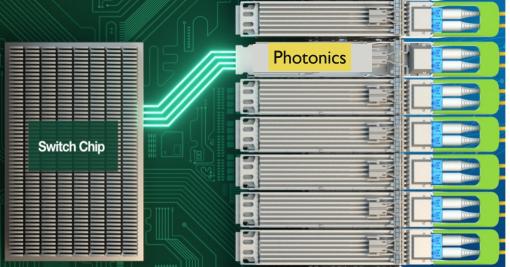


Linear-Drive Pluggable Optics (LPO)

Traditional pluggable optical modules



LPO Modules



- LPO means no DSP in the transceiver module
- How is this possible?
 - Broadcom Tomahawk5 and Jericho3 Switch Silicon serdes use advanced DSP technology
 - Requires expert system design and careful serdes tuning by networking vendors



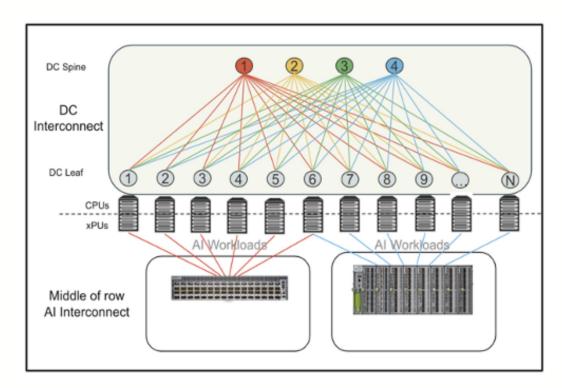
"Traditional" DSP Optics & LPO

Feature	"Traditional" DSP Optics	Linear Pluggable Optics (LPO)				
Power	~14W - 16W for 800G modules	~7W for 800G modules				
Latency	~100ns delay through DSP	~1ns delay through module				
Cost	\$X	~\$0.6X				
Technology Maturity	Mature, in high volume	New. Volume in late 2024 / Early 2025				
Ecosystem	Multi-vendor, plug and play, standards based	LPO MSA just announced LPO Modules will require tighter integration with the system Restricted to TH5/J3 platforms				
LPO offers significant power & cost advantages and improved MTBF						

Most 800G optics sold in 2024 will be DSP based optics.

Network Design for "Small" AI Applications

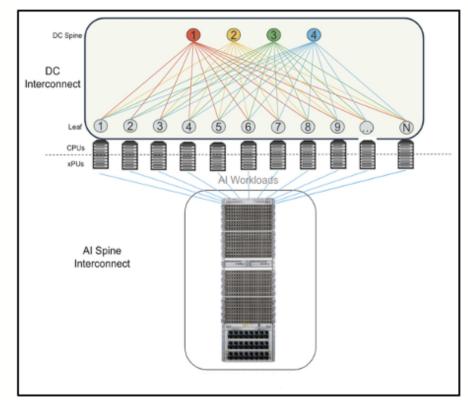
- Scale 64 x 400G or 128 x 200G xPU NICs
- Broadcom Tomahawk4
 - 64 x 400G QSFP-DD or OSFP
 - 25.6Tbps
- No Flow Collisions Single ASIC
- Handling incasts at the receiver:
 - ECN (Explicit Congestion Notification)
 - PFC (Priority Flow Control)
 - Standard buffer requires moderate tuning





Network Design for "Moderate" AI Applications

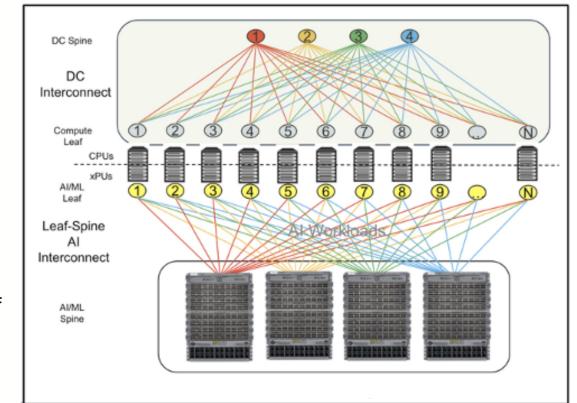
- Scale 576 x 400G xPU NICs
- Broadcom Jericho2/2C+
 - 576 x 400G QSFP-DD or OSFP
 - 230 Tbps
- AI Leaf and Spine in single chassis
- No Flow Collisions between line cards and fabric
 overprovisioned.
- High availability:
 - Redundant Fabric, Supervisor, Fan, PSU
- Handling incasts at the receiver
 - ECN and/or PFC
 - Deep buffer requires minimal tuning





Network Design for "Large" AI Applications

- Scale 18,432 x 400G xPU NICs
- Al Spine Broadcom Jericho2/2C+
 - 576 x 400G QSFP-DD or OSFP
 - 230 Tbps
- AI Leaf Broadcom Tomahawk4
 - 64 x 400G QSFP-DD or OSFP
 - 25.6Tbps
- Flow Collisions between AI Leaf and Spine
 - Requires Dynamic Load Balancing (DLB), Source LB
- High availability AI Fabric:
 - Requires ~1:1.2 over-provisioning on AI Leaf
- Handling incasts at the receiver
 - ECN and/or PFC
 - AI Leaf standard buffer requires extensive tuning





Thank You

ARISTA Al ready networks https://www.arista.com/en/solutions/ai-networking